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(54) **LIGHTING APPARATUS WITH A LIGHT SOURCE COMPRISING LIGHT EMITTING DIODES**

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See application file for complete search history.

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*F21V 29/00* (2015.01)

*F21K 99/00* (2016.01)

(Continued)

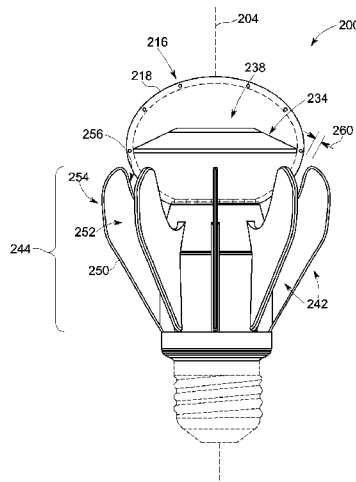
(52) **U.S. Cl.**

CPC ..... *F21V 29/20* (2013.01); *F21K 9/135* (2013.01); *F21K 9/50* (2013.01); *F21V 7/04*

(57) **ABSTRACT**

Embodiments of a lighting apparatus with a light source using one or more light emitting diodes (LEDs) to generate light. In one embodiment, the lighting apparatus comprises a light diffusing assembly that generates an optical intensity profile consistent with incandescent lamps. The light diffusing assembly comprises an envelope and a reflector element having frusto-conical member and an aperture element disposed therein. The lighting apparatus can also comprise a heat dissipating assembly with a plurality of heat dissipating elements disposed radially about the envelope. In one example, the heat dissipating elements are spaced apart from the envelope to promote convective heat dissipation.

**15 Claims, 9 Drawing Sheets**



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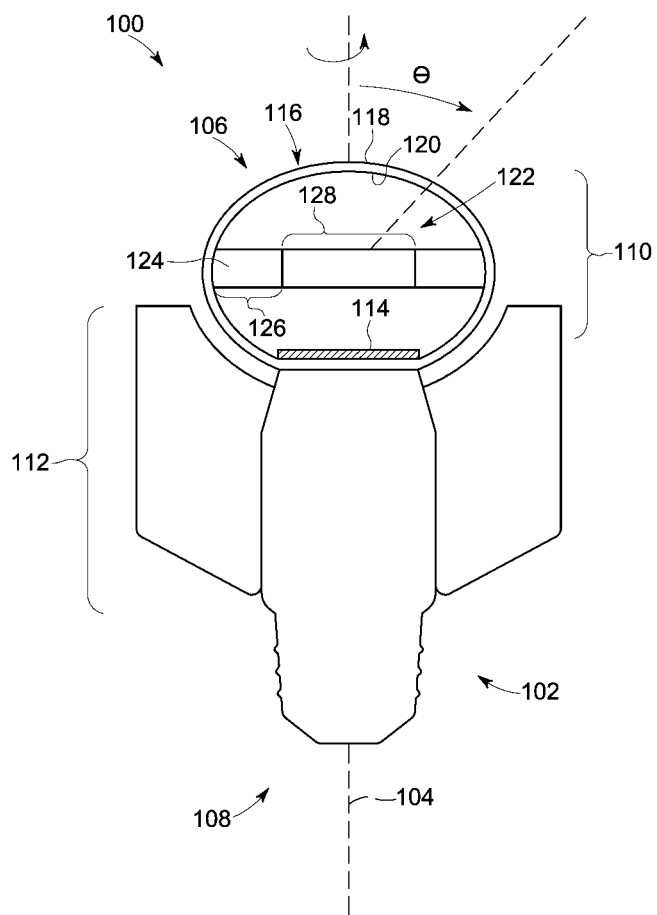


FIG. 1

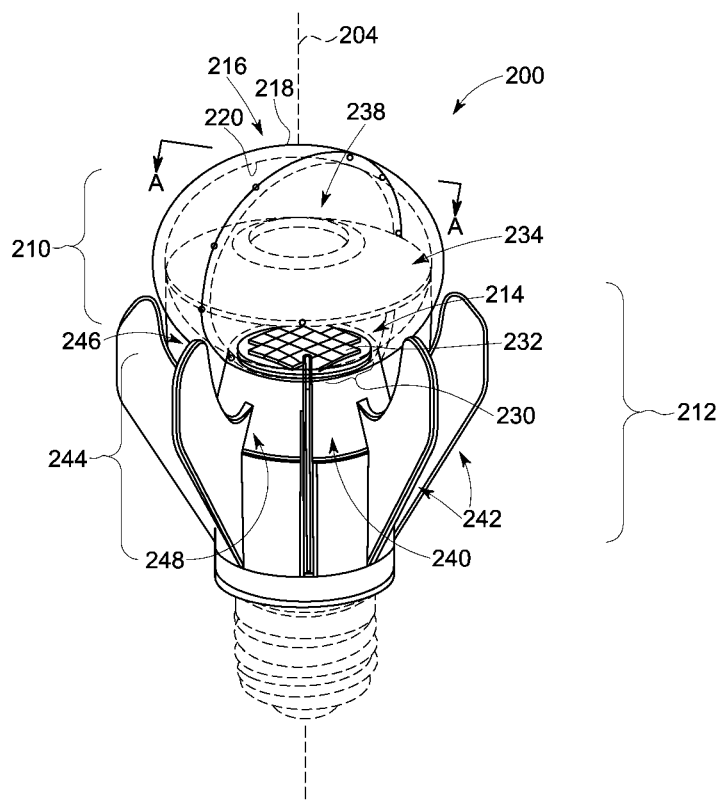


FIG. 2

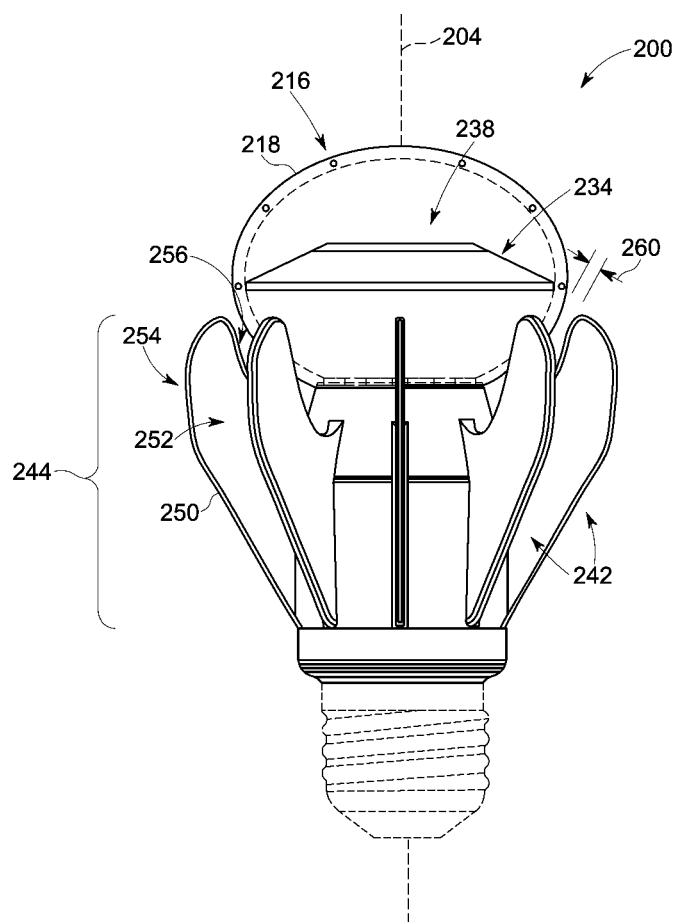


FIG. 3

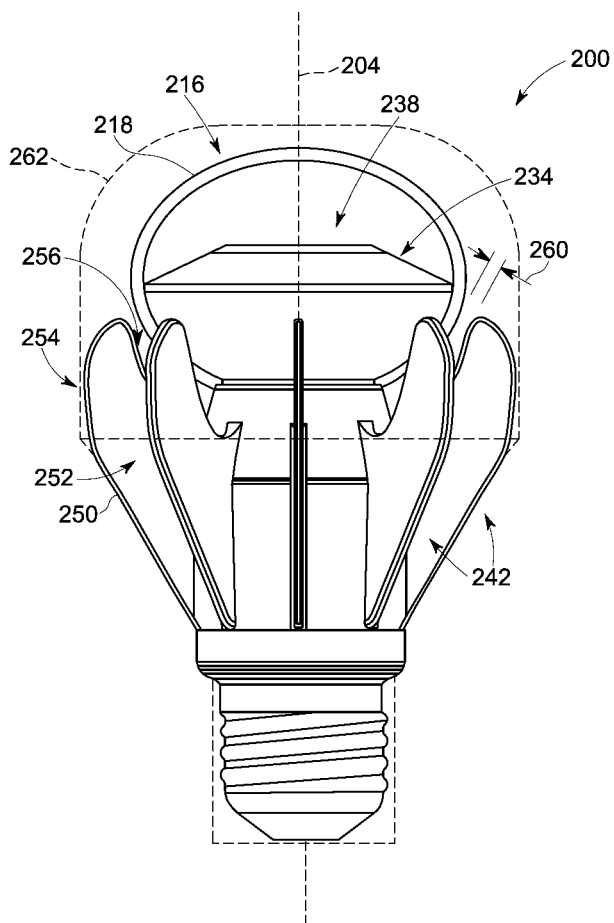


FIG. 4

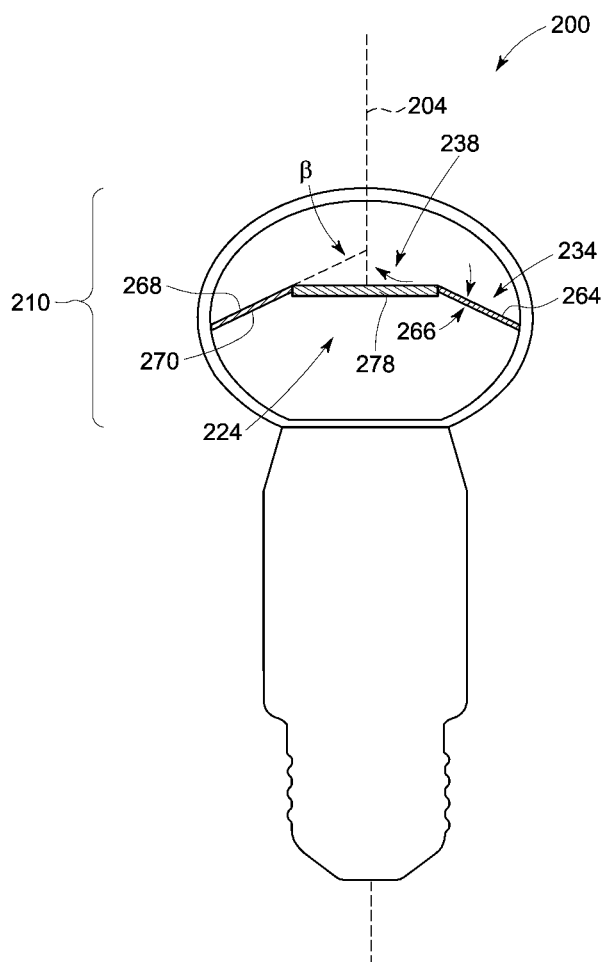


FIG. 5

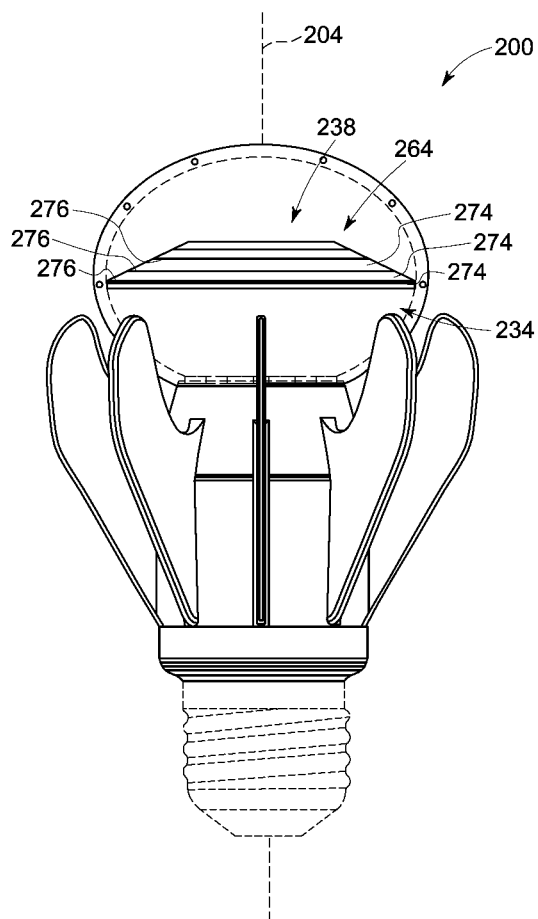


FIG. 6



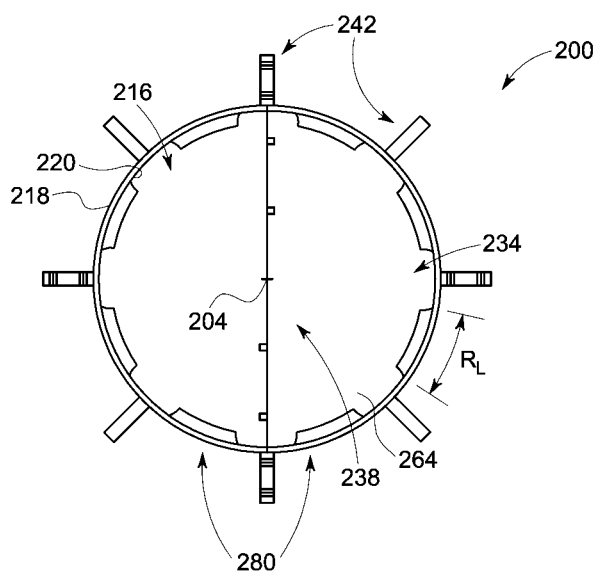


FIG. 7

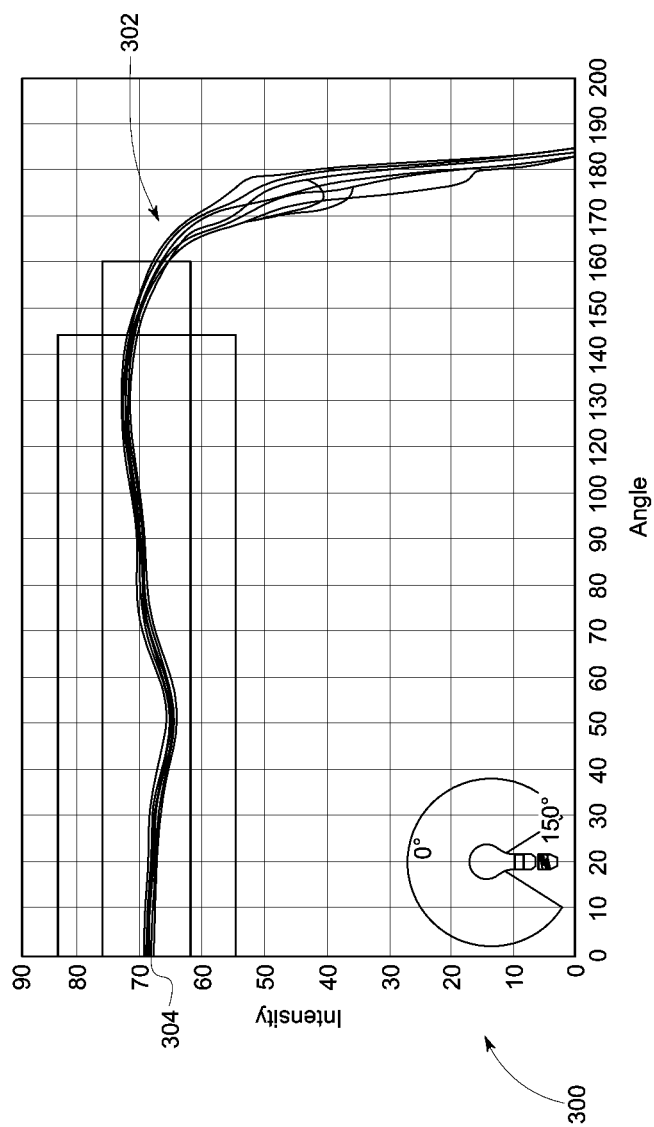


FIG. 8

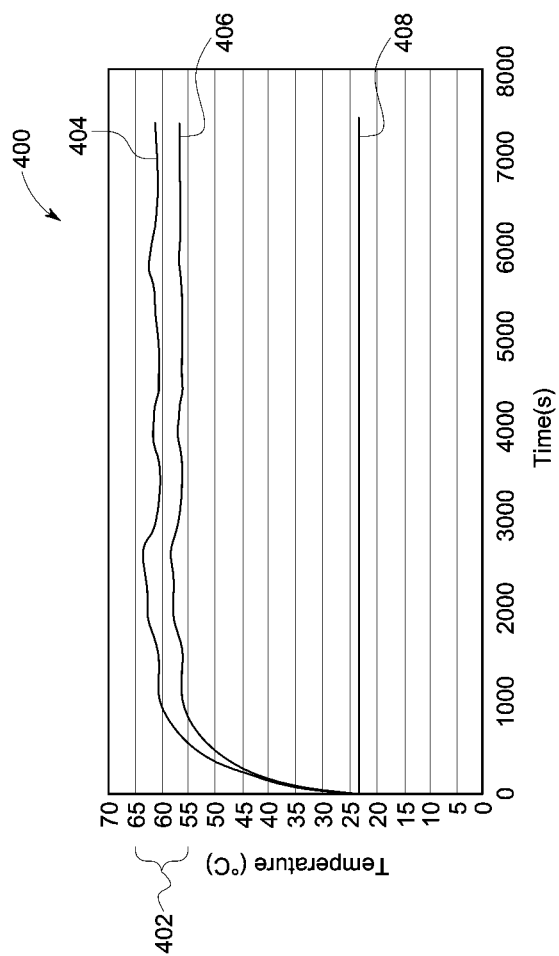


FIG. 9

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# LIGHTING APPARATUS WITH A LIGHT SOURCE COMPRISING LIGHT EMITTING DIODES

This application is a continuation of commonly-owned application Ser. No. 13/189,052, filed on 22 Jul. 2011 (now allowed), which is hereby incorporated by reference in its entirety.

## BACKGROUND

The subject matter of the present disclosure relates to lighting and lighting devices and, more particularly, to embodiments of a lighting apparatus using light-emitting diodes (LEDs), wherein the embodiments exhibit an optical intensity distribution consistent with common incandescent lamps.

Incandescent lamps (e.g., integral incandescent lamps and halogen lamps) mate with a lamp socket via a threaded base connector (sometimes referred to as an “Edison base” in the context of an incandescent light bulb), a bayonet-type base connector (i.e., bayonet base in the case of an incandescent light bulb), or other standard base connector. These lamps are often in the form of a unitary package, which includes components to operate from standard electrical power (e.g., 110 V and/or 220 V AC and/or 12 VDC). In the case of incandescent and halogen lamps, these components are minimal, as the lamp comprises an incandescent filament that operates at high temperature and efficiently radiates excess heat into the ambient. Many incandescent lamps are omni-directional light sources. These types of lamps provide light of substantially uniform optical intensity distribution (or, “optical intensity”). Such lamps find diverse applications such as in desk lamps, table lamps, decorative lamps, chandeliers, ceiling fixtures, and other applications where a uniform distribution of light in all directions is desired.

Solid-state lighting technologies such as LEDs and LED-based devices often have performance that is superior to incandescent lamps. This performance can be quantified by its useful lifetime (e.g., its lumen maintenance and its reliability over time). For example, whereas the lifetime of incandescent lamps is typically in the range about 1000 to 5000 hours, lighting devices that use LED-based devices are capable of operation in excess of 25,000 hours, and perhaps as much as 100,000 hours or more.

Unfortunately, LED-based devices are highly directional by nature. Common LED devices are flat and emit light from only one side. Thus, although superior in performance, the optical intensity of many commercially-available LED lamps intended as incandescent replacements is not consistent with the optical intensity of incandescent lamps.

Yet another challenge with solid-state technology is the need to adequately dissipate heat. LED-based devices are highly temperature-sensitive in both performance and reliability as compared with incandescent or halogen filaments. These features are often addressed by placing a heat sink in contact with or in thermal contact with the LED device. However, the heat sink may block light that the LED device emits and hence further limits the ability to generate light of uniform optical intensity. Physical constraints such as regulatory limits that define maximum dimensions for all lamp components, including light sources, further limit that ability to properly dissipate heat.

## BRIEF SUMMARY OF THE INVENTION

The present disclosure describes embodiments of a lighting apparatus with an optical intensity consistent with an

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incandescent lamp and with adequate heat dissipation to avoid problems with excess heat. Other features and advantages of the disclosure will become apparent by reference to the following description taken in connection with the accompanying drawings.

## BRIEF DESCRIPTION OF THE DRAWINGS

Reference is now made briefly to the accompanying drawings, in which:

FIG. 1 depicts a schematic diagram of a side view of one exemplary embodiment of a lighting apparatus;

FIG. 2 depicts a perspective view of another exemplary embodiment of a lighting apparatus;

FIG. 3 depicts a side view of the lighting apparatus of FIG. 2;

FIG. 4 depicts a side view of the lighting apparatus of FIG. 2 compared to an example of an industry standard lamp profile;

FIG. 5 depicts a cross-section, side view of the lighting apparatus taken along line A-A of FIG. 2;

FIG. 6 depicts a side view of the lighting apparatus of FIG. 2;

FIG. 7 depicts a top view of the lighting apparatus of FIG. 2;

FIG. 8 depicts a plot of an optical intensity distribution profile for an embodiment of a lighting apparatus such as the lighting apparatus of FIGS. 1, 2, 3, 4, 5, 6, and 7; and

FIG. 9 depicts a plot of LED board temperature profiles for two embodiments of a lighting apparatus such as the lighting apparatus of FIGS. 1, 2, 3, 4, 5, 6, and 7.

Where applicable like reference characters designate identical or corresponding components and units throughout the several views, which are not to scale unless otherwise indicated.

## DETAILED DESCRIPTION OF THE INVENTION

As used herein, an element or function recited in the singular and proceeded with the word “a” or “an” should be understood as not excluding plural said elements or functions, unless such exclusion is explicitly recited. Furthermore, references to “one embodiment” of the claimed invention should not be interpreted as excluding the existence of additional embodiments that also incorporate the recited features.

FIG. 1 illustrates an exemplary embodiment of a lighting apparatus 100. The lighting apparatus 100 comprises a base 102, a center axis 104, a north pole 106, and a south pole 108. The north pole 106 and the south pole 108 form a coordinate system that is useful to describe the spatial distribution of illumination that the lighting apparatus generates. The coordinate system is typically of the spherical coordinate system type, which in the present example comprises an elevation or latitude coordinate  $\theta$  and an azimuth or longitude coordinate  $\phi$ . For purposes of the discussion below, the latitude coordinate  $\theta=0^\circ$  at the north pole 106 and the latitude coordinate  $\theta=180^\circ$  at the south pole 108.

The lighting apparatus 100 also comprises a light diffusing assembly 110, a heat dissipating assembly 112, and a light source 114 which generates light. The light diffusing assembly 110 has an envelope 116, which in one example comprises light-transmissive material. The envelope 116 has an outer surface 118, an inner surface 120, and an interior volume 122. Inside of the interior volume 122, the light diffusing assembly 110 comprises a reflector element 124 with an outer reflective portion 126 and an inner transmissive portion 128.

At a relatively high level, embodiments of the lighting apparatus **100** generate light with a relative optical intensity distribution (or “optical intensity”) at a level of about  $100\pm 20\%$  over values of the latitude coordinate  $\theta$  of about  $0^\circ$  to about  $135^\circ$  or greater. In one embodiment, the lighting apparatus **100** maintains a relative optical intensity at a level of about  $100\pm 20\%$  at values of the latitude coordinate  $\theta$  of about  $0^\circ$  to about  $150^\circ$  or greater. In another embodiment, the lighting apparatus **100** maintains a relative optical intensity at a level of about  $100\pm 10\%$  at values of the latitude coordinate  $\theta$  of about  $0$  to about  $150^\circ$  or greater. These characteristics comply with target values for optical intensity that the Department of Energy defines for solid-state lighting products as well as other industry standards and ratings (e.g., Energy Star). For example, levels of optical intensity that the lighting apparatus **100** provides are suitable to replace common, incandescent light bulbs. Moreover, physical characteristics of the lighting apparatus **100** are consistent with the physical lamp profile of such incandescent light bulbs, where the outer dimension defines boundaries in which the lighting apparatus **100** must fit. Examples of this outer dimension meets one or more regulatory limits (e.g., ANSI, NEMA, etc.).

The envelope **116** can be substantially hollow and have a curvilinear geometry, e.g., spherical, spheroidal, ellipsoidal, toroidal, ovoidal, etc., that diffuses light. In some embodiments, the envelope **116** comprises a glass element, although this disclosure contemplates a variety of light-transmissive material such as diffusive plastics (e.g., diffusing polycarbonate) and/or diffusing polymers that diffuse light. Materials of the envelope **116** may be inherently light-diffusive (e.g., opal glass) or can be made light-diffusive in various ways such as by frosting and/or other texturing of the inside surface (e.g., the inner surface **120**) and/or the outer surface (e.g., the outer surface **118**) to promote light diffusion. In one example, the envelope **116** comprises a coating (not shown) such as enamel paint and/or other light-diffusive coating (available, for example, from General Electric Company, New York, USA). Suitable types of coatings are found on glass bulbs of some incandescent or fluorescent light bulbs. In still other examples, manufacturing techniques may embed light-scattering particles or fibers or other light scattering media in the material of the envelope **116**.

The reflector element **124** fits within the envelope **116** in a position to intercept light from the light source **114**. Fasteners such as adhesive can secure the peripheral edge of the reflector element **124** to the inner surface **120**. In some embodiments, the inner surface **120** and the reflector element **124** can comprise one or more complimentary features (e.g., a boss and/or a ledge), the combination of which secure the reflector element **124** in position. These features may form a snap-fit or have another mating configuration that prevents the reflector element **124** from moving.

The inner transmissive portion **128** is proximate the center axis **104**. Materials for the inner transmissive portion **128** may be a light diffuser comprising glass, plastic, ceramic, or surface diffusers and like materials that promote the scattering and transmission of light therethrough. Materials for the inner transmissive portion **128** may also be a light transmitter having minimal or no scattering, comprising glass, plastic, ceramic, or other optically transparent material. The inner transmissive portion **128** may also be an open aperture allowing light to transmit through without modification. The inner transmissive portion **128** may also be omitted.

In the present example, the outer reflective portion **126** bounds the inner transmissive portion **128** and has optical properties that reflect or transmit or scatter light or combina-

tion of reflection, transmission, and scattering of light. These optical properties may result from materials used to construct the reflector element **124** including the inner transmissive portion **128**. In some examples, the outer reflective portion **126** comprises an optically opaque and highly reflective material such as a solid polymer, ceramic, glass, or metal, or a reflective coating, or laminate on a substrate, etc. The reflected light may be specularly reflected, or diffusely reflected, or a combination of specularly and diffusely reflected. In one example, both sides of the reflector element **124** comprise a coating/laminate to form the outer reflective portion **126**. In some other examples, the outer reflective portion **126** comprises an optically reflective and transmissive material such as a solid polymer, ceramic, glass, or a reflective coating or laminate on a substrate, etc., that can reflect a portion of light and transmit a portion of light. The transmitted portion of light may be scattered or partially scattered or not scattered. The reflected portion of light may be specularly reflected, or diffusely reflected, or a combination of specularly and diffusely reflected. In still other examples, in lieu of distinctly arranged transmissive and reflective portions (e.g., the outer reflective portion **126** and the inner transmissive portion **128**), the reflector element **124** can have a pattern of one or more reflective elements and/or transmissive elements that cause the reflector element **124** to both transmit and reflect light.

Turning next to FIGS. **2**, **3**, **4**, **5**, **6**, and **7** another exemplary embodiment of a lighting apparatus **200** is shown. FIG. **2** depicts a perspective view of the lighting apparatus **200** and FIGS. **3**, **4** and **6** illustrate a side view of the lighting apparatus **200**. FIG. **5** illustrates a cross-section of the lighting apparatus **200** taken along line A-A (FIG. **2**). FIG. **7** illustrates a top view of the lighting apparatus **200**. Like numerals are used to identify like components as between FIG. **1** and FIGS. **2**, **3**, **4**, **5**, **6** and **7**, except that the numerals are increased by 100 (e.g., 100 in FIG. **1** is now 200 in FIGS. **2**, **3**, **4**, **5**, **6**, and **7**). For example, embodiments of the lighting apparatus **200** comprise a center axis **204**, a light diffusing assembly **210**, a heat dissipating assembly **212**, and a light source **214**. The light diffusing assembly **210** comprises an envelope **216** with an outer surface **218** and an inner surface **220**.

In FIG. **2**, the light source **214** comprises a solid-state device **230** with one or more light-emitting elements **232**, e.g., light-emitting diodes (LEDs). The reflector element **224** comprises a cone element **234** and an aperture element **238**. The heat dissipating assembly **212** comprises a base element **240**, in thermal contact with the light source **214**, and one or more heat dissipating elements **242** coupled to the base element **240**. The heat dissipating elements **242** promote conduction, convection, and radiation of heat away from the light source **214**. For example, the heat dissipating elements **242** have an element body **244** with a tip end **246** and a base end **248** that can conduct thermal energy from the base element **240**.

The solid-state device **230** can comprise a planar LED-based light source that emits light into a hemisphere having a nearly Lambertian intensity distribution, compatible with the light diffusing assembly **210** for producing omni-directional illumination distribution. In one embodiment, the planar LED-based Lambertian light source includes a plurality of LED devices (e.g., LEDs **232**) mounted on a circuit board (not shown), which is optionally a metal core printed circuit board (MCPCB). The LED devices may comprise different types of LEDs. For example, the solid-state device **230** may comprise one or more first LED devices and one or more second LED devices having respective spectra and intensities that mix to render white light of a desired color temperature and color rendering index (CRI). In one embodiment, the first LED

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devices output white light, which in one example has a greenish rendition (achievable, for example, by using a blue- or violet-emitting LED chip that is coated with a suitable “white” phosphor). The second LED devices output red and/or orange light (achievable, for example, using a GaAsP or AlGaInP or other epitaxy LED chip that naturally emits red and/or orange light). The light from the first LED devices and second LED devices blend together to produce improved color rendition. In another embodiment, the planar LED-based Lambertian light source can also comprise a single LED device or an array of LED emitters incorporated into a single LED device, which may be a white LED device and/or a saturated color LED device and/or so forth. In another embodiment, the LED emitter are organic LEDs comprising, in one example, organic compounds that emit light.

As best shown in FIG. 3, the element body **244** of the heat dissipating elements **242** has a peripheral edge **250** that forms the outer periphery or shape of the heat dissipating elements **242**. Each of the heat dissipating elements **242** have an element surface **252** on the front and back of the element body **244**. The peripheral edge **250** comprises an outer peripheral edge **254** and an inner peripheral edge **256** proximate the outer surface **218** of the envelope **216**. A gap **260** separates the inner peripheral edge **256** from the outer surface **218** of the envelope **216**.

The gap **260** spaces the tip end **246** of the heat dissipating elements **242** away from the outer surface **218** of the envelope **216**. Generally the gap **260** is smaller at tip end **246** than at the base end **248**. Surprisingly, this configuration improves heat dissipation and reduces the LED board temperature by about 5° C. at least as compared to other designs in which all or a portion of the heat dissipating element **242** nearly contacts the envelope **216**. It is believed that the gap **260** provides space between the inner peripheral edge **256** and the outer surface **218** to facilitate air flow and convection currents. The space effectively reduces friction and drag on the air, which improves air flow over the outer surface **218** of the envelope **216**, the front and back faces of the element body **244**, and the inner peripheral edge **256**. The improved flow of air increases the rate of convection and the rate of heat dissipation. In one embodiment, the gap **260** at the tip end **246** is from about 1.75 mm to about 3 mm, about 2 mm or greater and, in one example, the gap **260** is about 3 mm or more. In one embodiment the gap **260** at the base end **248** is greater than the gap **260** at the tip end **246**, where the gap **260** can be from about 3 mm to about 10 mm or more.

In addition to the lighting apparatus **200**, FIG. 4 shows that the outer peripheral edge **254** fits within a lamp profile **262**, the extent of which is defined by an outer dimension D, which can be from about 60 mm (e.g., typical of a GE A19 incandescent lamp) to about 69.5 mm (e.g., the maximum diameter allowed by ANSI for an A19 lamp). Embodiments of the lighting apparatus **200** are amenable to many other examples of the lamp profile **262**. Some examples include A-type (e.g., A15, A19, A21, A23, etc.) and G-type (e.g., G20, G30, etc.) as well as other profiles that various industry standards known and recognized in the art define.

In designing the heat dissipating assembly **212**, the limiting thermal impedance in a passively cooled thermal circuit is typically the convective impedance to ambient air (that is, dissipation of heat into the ambient air). It is generally simpler to optimize the thermal conduction through the bulk of the heat dissipating assembly **212** than it is to optimize the convection and radiation to ambient from the heat dissipating assembly **212**. Furthermore, the convective heat transfer to ambient from the heat dissipating assembly **212** is generally much greater than the radiative heat transfer to ambient from

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the heat dissipating assembly **212**. So, to achieve the most effective cooling of the LEDs, it is required to minimize the thermal impedance of the convective heat transfer to ambient from the heat dissipating assembly **212**.

This convective impedance is generally proportional to the surface area of the heat dissipating assembly **212**. In the case of a replacement lamp application, where the lighting apparatus **200** must fit into the same space as the traditional Edison-type incandescent lamp being replaced (e.g., into the lamp profile **262**), there is a fixed limit on the available amount of surface area of the imaginary outside element profile. Therefore, it is advantageous to increase the available surface area that is in contact with ambient air as much as possible for heat dissipation into the ambient, such as by placing the heat dissipating elements **242** or other heat dissipating structures around or adjacent to the light source **214**, and by maximizing the surface area of each of the heat dissipating elements **242**, and by maximizing the number of heat dissipating elements **242**, while maintaining a minimal blockage of light from the envelope **116**. Functionally, however, the configuration of the heat dissipating elements **242** may be required to vary to meet not only the physical lamp profile (e.g., the lamp profile **262**) of current regulatory limits (ANSI, NEMA, etc.), but also to satisfy consumer aesthetics or manufacturing constraints as well.

Thermal properties of the heat dissipating elements **242** can have a significant effect on the total energy that the heat dissipating assembly **212** dissipates and, accordingly, the temperature of the solid-state device **230** and any corresponding driver electronics. Since the performance and reliability of the solid-state device **230** and driver electronics is generally limited by operating temperature, it is critical to select one or more materials with appropriate properties. The thermal conductivity of a material defines the ability of a material to conduct heat. Since the solid-state device **230** may have a very high heat density, the heat dissipating assembly **212** should preferably comprise materials with high thermal conductivity so that the generated heat can be conducted through a low thermal resistance away from the solid-state device **230**.

In general, metallic materials have a high thermal conductivity, with common structural metals such as alloy steel, cast aluminum, extruded aluminum, copper, or engineered composite materials such as thermally-conductive polymers. Exemplary materials can exhibit thermal conductivities of about 50 W/m-K, from about 80 W/m-K to about 100 W/m-K, 170 W/m-K, 390 W/m-K, and from about 1 W/m-K to about 30 W/m-K, respectively. A high conductivity material will allow more heat to move from the thermal load to ambient and result in a reduction in temperature rise of the thermal load. The heat dissipating assembly **212** (e.g., the base element **240** and the heat dissipating elements **242**) can comprise one or more high thermal conductivity materials including metals (e.g., aluminum), plastics, plastic composites, ceramics, ceramic composite materials, nano-materials, such as carbon nanotubes (CNT) or CNT composites.

Practical considerations, such as manufacturing process or cost, may affect the selection of materials and the effective thermal properties. For example, cast aluminum, which is generally less expensive in large quantities, has a thermal conductivity value approximately half of extruded aluminum. It is preferred for ease and cost of manufacture to use predominantly one material for the majority of the heat dissipating assembly **212** (e.g., the base element **240** and the heat dissipating elements **242**), but combinations of cast/extrusion methods of the same material or even incorporating two or more different materials into construction of the heat dissipating assembly **212** to maximize cooling are also possible.

Embodiments of the lighting apparatus 200 can comprise 3 or more heat dissipating elements 242 arranged radially about the center axis 204. The heat dissipating elements 242 can be equally spaced from one another so that adjacent ones of the heat dissipating elements 242 are separated by at least about 45° for an 8-fin apparatus and 22.5° for an 18-fin apparatus measured along the longitude coordinate (p. Physical dimensions (e.g., width, thickness, and height) can also determine the necessary separation between the heat dissipating elements 242 as well as other physical aspects of the lighting apparatus 200.

Moreover, the physical dimensions, placement, and configuration of the heat dissipating elements 242 may also impact a variety of lighting characteristics, including the optical intensity of the lighting apparatus 200. For example, the width of the heat dissipating elements 242 affects primarily the latitudinal uniformity of the light distribution, the thickness of the heat dissipating elements 242 affects primarily the longitudinal uniformity of the light distribution, and the height of the heat dissipating elements 242 affects how much of the latitudinal uniformity is disturbed. In general terms, in order to minimize the distortion of the light intensity distribution the same fraction of the emitted light should interact with the heat dissipating elements 242 at all angles  $\theta$ . In functional terms, to maintain the existing light intensity distribution of the light diffusing assembly 210, the area of the element surfaces 252 in view of the light source 214 created by the width and thickness of the heat dissipating elements 242 should stay in a constant ratio with the surface area of the emitting light surface that they encompass.

The heat dissipating assembly 212 can also have optical properties that affect the resultant optical intensity. When light impinges on a surface, it can be absorbed, transmitted, or reflected. In the case of most engineering thermal materials, they are opaque to visible light, and hence, visible light can be absorbed or reflected from the surface. In consideration of optical properties, selection and design of the light apparatus 200 should contemplate the optical reflectivity efficiency, optical specularity, and the size and location of the heat dissipating elements 242. As discussed hereinbelow, concerns of optical efficiency, optical reflectivity, and intensity will refer herein to the efficiency and reflectivity the wavelength range of visible light, typically about 400 nm to about 700 nm.

The absolute reflectivity of the surface of the heat dissipating elements 242 will affect the total efficiency of the lighting apparatus 200 as well as the intrinsic light intensity distribution of the light source 214. Though only a small fraction of the light emitted from the light source 214 may impinge the heat dissipating assembly 212 with heat dissipating elements 242 arranged around the light source 214, if the reflectivity is very low, a large amount of flux will be lost on the element surfaces 252 of the heat dissipating elements 242, and reduce the overall efficiency of the lighting apparatus 200.

The optical intensity is affected by both the redirection of emitted light from the light source 214 and also absorption of flux by the heat dissipating assembly 212. In one embodiment, if the reflectivity of the heat dissipating elements 242 is kept at a high level, such as greater than 70%, the distortions in the optical intensity can be minimized. Similarly, the longitudinal and latitudinal intensity distributions can be affected by the surface finish of the thermal heat sink and surface enhancing elements. Smooth surfaces with a high specularity (mirror-like) distort the underlying intensity distribution less than diffuse (Lambertian) surfaces as the light is directed outward along the incident angle rather than perpendicular to the surface of the heat dissipating elements 242.

The thermal emissivity, or efficiency of radiation in the far infrared region (approximately 5-15  $\mu\text{m}$ ) of the electromagnetic radiation spectrum, is also an important property for the surfaces of the heat dissipating elements 242. Generally, very shiny metal surfaces have very low emissivity, on the order of 0.0-0.2. Hence, some sort of coating or surface finish may be desirable, such as paints (0.7-0.95) or anodized coatings (0.55-0.85). A high emissivity coating on the heat dissipating elements 242 may dissipate approximately 40% more heat than bare metal with low emissivity. Selection of a high-emissivity coating must also take into account the optical properties of the coating, as low reflectivity or low specularity in the visible wavelength can adversely affect the overall efficiency and light distribution of the lighting apparatus 100.

A range of surface finishes, varying from a specular (reflective) to a diffuse (Lambertian) surface can be selected for the heat dissipating elements 242. The specular designs can be a reflective base material or an applied highly specular coating. The diffuse surface can be a finish on the heat dissipating elements 242, or an applied paint or powder coating or foam or fiber mat or other diffuse coating. Each provides certain advantages and disadvantages. For example, a highly reflective surface may have the ability to maintain the light intensity distribution, but may be thermally disadvantageous due to the generally lower emissivity of bare metal surfaces. Or a highly diffuse, high-reflectivity coating may require a thickness that provides a thermally insulating barrier between the heat dissipating elements 242 and the ambient air.

In addition, highly specular surfaces may be difficult to maintain over the life of the lighting apparatus 200, which is typically 25,000-50,000 hours. A visibility transparent coating may be applied over the specular surface to improve the resistance to abrasion and oxidation of the surface. Further if the visibly transparent coating has a high emittance in the infrared, then the thermal radiation may be desirably enhanced. In one embodiment, the heat diffusing elements 242 can comprise a diffuse surface. The maintenance of the diffuse surface might be robust over the life of the lighting apparatus than a specular surface, and can also provide a visual appearance that is similar to existing incandescent omnidirectional light sources. A diffuse finish might also have an increased thermal emissivity compared to a specular surface which will increase the heat dissipation capacity of the heat sink, as described above. In one example, the coating will possess a highly specular surface and also a high emissivity, examples of which would be highly specular paints, or high emissivity coatings over a highly specular finish or coating.

The cross-section of FIG. 5 and the top view of FIG. 6 shows one configuration of the reflector element 224. In FIG. 5, the cone element 234 has a frusto-conical member 264 with a thin-wall profile 266, an upper surface 268, and a lower surface 270. The frusto-conical member 264 forms an angle  $\beta$  with the center axis 204. In one embodiment, the angle  $\beta$  may be less than 90°, in which case the frusto-conical member 264 has its larger diameter at the bottom and its smaller diameter at the top, as shown in FIG. 5. In one embodiment, the angle  $\beta$  may be 90°, in which case the frusto-conical member 264 simplifies to a flat circle and, in construction, the flat circuit comprises an aperture at the center. In another embodiment, the angle  $\beta$  may be greater than 90°, so that the frusto-conical member 264 is inverted. In yet another embodiment, the frusto-conical member 264 might be a combination of multiple frusto-conical members, one or more of which has different angle  $\beta$  and joined together, e.g., at their edges. An example of this multiple-member construction is shown in

FIG. 6, wherein the frusto-conical member **264** comprises a plurality of members **274** with edges **276** abutting adjacent members.

Referring back to FIG. 5, the aperture element **238** comprises a circular member **278** that is aligned with the center axis **204**. The specific dimensions of each optical element (e.g., the frusto-conical member **264**, the circular member **278**, the lighting assembly **210**, etc.) to be used for any target relative optical distribution will depend on a combination (1) LED light source (or “engine”) size and native optical distribution determined by standard source imaging goniometers, and (2) optical properties (e.g., scattering, transmittance, reflectance, absorption, etc.) of the envelop, cone element and surface, annular surface, and coatings on the heating dissipating element. In one example, where a low loss surface diffuser is used in the annulus the circular member **278** can have a diameter of about 10 mm to about 20 mm or greater, as measured about the center axis **204**. In other examples, the diameter can range from about 1 mm to about 60 mm. Other shapes (other than circular) are also possible for the aperture element **238** including square, rectangular, polygonal, annular, etc. In another embodiment, the circular member **278** may be three-dimensional with a surface geometry such as a frusto-conical, conical, hemispherical, and the like.

The thin-wall profile **266** can have thickness from about 0.5 mm to about 3 mm or more and/or, for example, of suitable thickness to provide the relative optical intensity as described above. In one embodiment, one or more of the upper surface **268** and the lower surface **270** can have a coating disposed thereon. Values for the angle  $\beta$  can be from about 45° to about 135°, and in one example from about 55° to about 75° and, in another example the angle  $\beta$  is 65° or greater.

In FIG. 7, the frusto-conical member **264** comprises a plurality of slots **280** found between the peripheral edge of the frusto-conical member **264** and the inner surface **220** of the envelope **216**. In one embodiment, the frusto-conical member **264** includes the slots **280** to provide the lighting apparatus **200** with a more appealing and/or aesthetically pleasing appearance by allowing light to illuminate the envelope **216** near the edge of the frusto-conical member **264** to reduce the bright-dark contrast that otherwise is visible at the edge. The slots **274** can be spaced radially about the center axis **204**. Each of the slots **274** can have a radial length ( $R_L$ ), which can vary as desired. For example, the radial length ( $R_L$ ) can vary from slot-to-slot, or the slots **274** can be configured so the radial length ( $R_L$ ) is uniform among the plurality of slots **274**. In one embodiment, the slots **274** comprise about 2% (slot width/cone diameter) and/or about 10% of the total area of the frusto-conical member **264**.

The slots **280** may be in any other geometric shape or size of opening so as to provide a region within the frusto-conical member **264** where light is transmitted through to the envelope **216**. This feature can enhance the light intensity distribution near the north pole (e.g., the north pole **106** (FIG. 1)) or to provide a more uniformly lit appearance on the surface of the envelope **216**. For example, the slots **280** might be circles, ellipses, polygons, or any other shape. The slots **280** may be positioned at or near the edge of the frusto-conical member **264** or at or near the circular member **272**, or anywhere in between. The slots **280** may be voids of air, or may be filled with any of the materials that are available for use in the circular member **272** which allow transmission of light.

The following example further illustrates various aspects and embodiments of the present invention.

#### EXAMPLE

In one embodiment, a lighting apparatus (e.g., the lighting apparatus **100**, **200** of FIGS. 1, 2, 3, 4, 5, 6, and 7) comprises the following:

An example of an envelope (e.g., the envelope **116**, **216** of FIGS. 1, 2, 3, 4, and 5) comprising a Teijin ML5206 low loss diffuser having a spheroidal shape with dimensions of 53 mm×53 mm×39 mm.

An example of a reflector element (e.g., the reflector element **124**, **224** of FIGS. 1, 2, 3, 4, 5, 6, and 7). The reflector element comprises a cone element (e.g., the cone element **234** of FIGS. 4, 5, 6, and 7) comprising a slotted polycarbonate cone with high-reflectance paint and/or high-reflectance self-adhesive laminates and/or integral molded high-reflectance white plastics. The reflector element also comprises an aperture element (e.g., the aperture element **238** of FIGS. 3, 4, 5, 6, and 7) comprising an 80° surface diffuser center aperture, wherein 80° is the full-width at half-maximum (FWHM) of the intensity distribution of light scattered by the diffuser.

An example of a light source (e.g., the light source **114**, **214** of FIGS. 1 and 2) comprises a circular LED package on board assembly.

An example of a heat dissipating assembly (e.g., the heat dissipating assembly **112**, **212** of FIGS. 1 and 2) comprises eight (8) heat dissipating elements (e.g., the heat dissipating elements **242** of FIGS. 2, 3, and 4) comprising Al 6061, wherein each of the heat dissipating elements comprises a high reflectance outdoor coating and/or high-reflectance powder coating.

FIG. 8 illustrates a plot **300** of an optical intensity distribution profile **302** (or “optical intensity” profile **302**). Data for the plot **300** was gathered using a Mirror Goniometer from the embodiment of the lighting apparatus having features described above. As the optical intensity profile **302** illustrates, the lighting apparatus achieves a mean optical intensity **304** of about 100±10% at an angle (e.g., the latitude coordinate  $\theta$  of FIG. 1) up to at least 150°.

FIG. 9 illustrates a plot **400** of thermal profiles **402** comprising an 8-fin profile **404** and a 12-fin profile **406**. The thermal profiles **402** also comprise an ambient profile **408**. Data for the plot **400** was gathered using a thermocouple secured to one of the heat dissipating elements on the embodiment of the lighting apparatus having features described above. As the 8-fin profile **404** illustrates, the lighting apparatus achieves a mean temperature of 62° C. when measured in a 25° C. ambient.

Table 1 below summarizes data for color uniformity for the embodiment of the lighting apparatus having features described above. The data was gathered using a Mirror Goniometer.

TABLE 1

$\theta$	Du*v*			
	0	90	180	270
0	0.0016	0.0018	0.0018	0.0019
10	0.0020	0.0020	0.0019	0.0019
20	0.0017	0.0019	0.0017	0.0016
30	0.0016	0.0019	0.0016	0.0012
40	0.0013	0.0017	0.0016	0.0011
50	0.0010	0.0013	0.0019	0.0009
60	0.0010	0.0009	0.0023	0.0015
70	0.0014	0.0014	0.0024	0.0020
80	0.0018	0.0024	0.0025	0.0021
90	0.0017	0.0026	0.0018	0.0014
100	0.0018	0.0027	0.0014	0.0011
110	0.0016	0.0024	0.0011	0.0011
120	0.0015	0.0020	0.0008	0.0010
130	0.0013	0.0017	0.0006	0.0005
140	0.0012	0.0018	0.0004	0.0003
150	0.0009	0.0016	0.0004	0.0005



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Note the color uniformity that the data of Table 1 illustrates.

A sample of embodiments of a lighting apparatus is provided below in which:

In embodiment A, a lighting apparatus, comprising a light diffusing assembly comprising an envelope and a reflector element; and a light source comprising a solid-state device, wherein the light diffusing assembly can disperse light from the solid-state device with an optical intensity distribution of  $100\pm 20\%$  over a latitude coordinate  $\theta$  of  $135^\circ$  or better.

The lighting apparatus of embodiment A, further comprising a plurality of heat dissipating elements disposed radial about the envelope.

The lighting apparatus of embodiment A, wherein the envelope comprises a spheroid shape.

The lighting apparatus of embodiment A, wherein the reflector element comprises an outer reflective portion and an inner transmissive portion.

In embodiment B, a lamp, comprising an envelope from which light can be emitted; and a plurality of heat dissipating elements disposed radially about the envelope, the heat dissipating elements having a tip end spaced apart from the envelope to form an air gap, wherein light from the envelope exhibits an optical intensity of  $100\pm 20\%$  over a latitude coordinate  $\theta$  of  $135^\circ$  or better.

The lamp of embodiment B, wherein the air gap is at least 3 mm.

The lamp of embodiment B, wherein the heat dissipating elements fit within a form factor defined by ANSI standard for A19 lamps.

The lamp of embodiment B, wherein the heat dissipating elements are equally-spaced radially apart from one another.

The lamp of embodiment B, wherein the heat dissipating elements comprise a reflective coating.

The lamp of embodiment B, further comprising a light source in thermal contact with the heat dissipating elements, wherein the light source comprises a plurality of light emitting diodes.

This written description uses examples to disclose embodiments of the invention, including the best mode, and also to enable any person skilled in the art to practice the invention, including making and using any devices or systems and performing any incorporated methods. The patentable scope of the invention is defined by the claims, and may include other examples that occur to those skilled in the art. Such other examples are intended to be within the scope of the claims if they have structural elements that do not differ from the literal language of the claims, or if they include equivalent structural elements with insubstantial differences from the literal language of the claims.

What is claimed is:

1. A lighting apparatus, comprising:

an envelope forming an interior volume and comprising light-transmissive material;

a heat dissipating assembly comprising a plurality of heat dissipating elements arranged radially about a center axis;

a reflector element disposed in the interior volume, wherein the reflector element comprises an aperture element disposed at the center axis; and

a light source in thermal contact with the heat dissipating assembly.

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2. The lighting apparatus of claim 1, wherein the light source comprises one or more light emitting diodes.

3. The lighting apparatus of claim 1, wherein the light source comprises one or more organic light emitting diodes.

4. The lighting apparatus of claim 1, wherein heat dissipating elements have a tip end proximate the envelope, and wherein the air gap at the tip end is about 2 mm or greater.

5. The lighting apparatus of claim 1, wherein the heat dissipating elements fit within an A-type lamp profile or a G-type lamp profile.

6. The lighting apparatus of claim 1, wherein the plurality of heat dissipating elements are spaced-apart from the envelope forming an air gap.

7. The lighting apparatus of claim 1, wherein the plurality of heat dissipating elements are substantially equally spaced from one another.

8. A lighting apparatus, comprising:

an envelope forming an interior volume and comprising light-transmissive material;

a heat dissipating assembly comprising a plurality of heat dissipating elements arranged radially about a center axis;

a reflector element disposed in the interior volume, wherein the reflector element comprises an aperture element disposed at the center axis; and

a light source in thermal contact with the heat dissipating assembly;

wherein the plurality of heat dissipating elements have a base end below the envelope and a body element that extends from the base end, the body element terminating at a tip end proximate the envelope.

9. A lighting apparatus, comprising:

an envelope forming an interior volume and comprising light-transmissive material;

a reflector element disposed in the interior volume, wherein the reflector element comprises an aperture element disposed at a center axis of the lighting apparatus; and

a light source comprising one or more light emitting diodes.

10. The lighting apparatus of claim 9, wherein the reflector element comprises a frusto-conical member.

11. The lighting apparatus of claim 10, wherein the frusto-conical member tapers from its center axis toward the envelope.

12. The lighting apparatus of claim 9, wherein the reflector element comprises one or more slots disposed radially about the center axis and positioned between the reflector element and the envelope.

13. The lighting apparatus of claim 9, wherein the aperture element comprises a circular member aligned with the center axis.

14. The lighting apparatus of claim 9, wherein said lighting apparatus exhibits an optical intensity distribution of about  $100\pm 20\%$  over a latitude coordinate  $\theta$  of about  $135^\circ$  or greater.

15. The lighting apparatus of claim 9, wherein said lighting apparatus exhibits an optical intensity distribution of about  $100\pm 10\%$  over a latitude coordinate of about  $150^\circ$  or greater.

\* \* \* \* \*